

## (19) United States

# (12) Patent Application Publication (10) Pub. No.: US 2022/0361330 A1 Oyaizu et al.

Nov. 10, 2022 (43) **Pub. Date:** 

### (54) WIRING SUBSTRATE

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Appl. No.: 17/630,630

(22) PCT Filed: Jul. 16, 2021

(86) PCT No.: PCT/JP2021/026731

§ 371 (c)(1),

Jan. 27, 2022 (2) Date:

#### (30)Foreign Application Priority Data

Nov. 18, 2020 (JP) ...... 2020-191768

### **Publication Classification**

(51) Int. Cl. H05K 1/11 (2006.01)

U.S. Cl. (52)

CPC ... H05K 1/113 (2013.01); H05K 2201/09481 (2013.01); H05K 2201/09563 (2013.01); H05K 2201/09545 (2013.01); H05K 2201/0305 (2013.01)

#### (57)**ABSTRACT**

A wiring substrate includes a first insulating layer, a first conductor layer, and a plurality of filled vias. The first insulating layer has a first surface and a second surface positioned on a side opposite to the first surface. The first conductor layer is formed on the first surface of the first insulating layer. The plurality of filled vias are formed inside the first insulating layer. The plurality of filled vias each have a structure in which a via hole penetrating the first insulating layer is filled with a metal. The first conductor layer includes a pad. The pad overlaps the plurality of filled vias in a plan view from a thickness direction of the first insulating layer and is connected to the plurality of filled vias.

